

# APPROVAL SHEET

# **WR02X(W)**

±5%, ±1%

RoHS compliant and Lead content 100ppm General purpose chip resistors Size 0201

\*Contents in this sheet are subject to change without prior notice.



#### **FEATURE**

- 1. Small size and light weight
- 2. High reliability and stability
- 3. Reduced size of final equipment
- 4. Suitable for high density print circuit board assembly
- 5. Higher component and equipment reliability
- 6. RoHS compliant and Lead free product

# **APPLICATION**

- 1. Mobile phone
- 2. PDA
- 3. Camcorders
- 4. Palmtop computers
- 5. Hybrid module

#### DESCRIPTION

The **LEAD FREE** resistors are constructed in a high grade ceramic body (aluminum oxide). Internal metal electrodes are added at each end and connected by a **LEAD FREE** resistive paste that is applied to the top surface of the substrate. The composition of the paste is adjusted to give the approximate resistance required and the value is trimmed to nominated value within tolerance which controlled by laser trimming of this resistive layer.

The resistive layer is covered with a **BLACK** protective coat. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Tin ( **LEAD FREE** ) alloy.

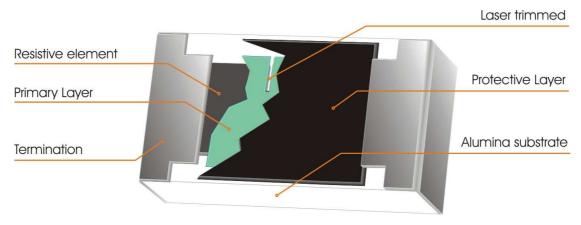


Fig 1. Construction of Chip-R WR02X



#### **QUICK REFERENCE DATA**

| Item                                      | General Specification |                      |  |
|---|-----------------------|----------------------|--|
| Series No.                                | W                     | R02X(W)              |  |
| Size code                                 | 02                    | 201(0603)            |  |
| Resistance Range                          | 1Ω~10MΩ ( ±5          | % tolerance), Jumper |  |
|   | 1Ω~1ΜΩ                | ( ±1% tolerance )    |  |
| Resistance Tolerance                      | ±1%                   | ±5%                  |  |
|   | E96/E24               | E24                  |  |
| TCR (ppm/°C)                              | 100Ω - 10MΩ, ±200     |                      |  |
|   | 10Ω - 97.6Ω, +600 ~ 0 |                      |  |
|   | 1 - 9.76Ω, +800~ -100 |                      |  |
| Max. dissipation @ T <sub>amb</sub> =70°C | 1/20 W                |                      |  |
| Max. Operation Voltage (DC or RMS)        | 25V                   |                      |  |
| Max. Overload Voltage (DC or RMS)         | 50V                   |                      |  |
| Climatic category (IEC 60068)             | 5                     | 5/125/56             |  |

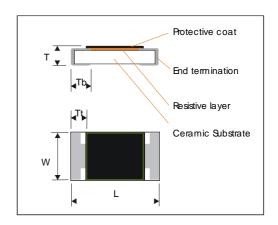
#### Note:

- 1. This is the maximum voltage that may be continuously supplied to the resistor element, see "IEC publication 60115-8"
- 2. Max. Operation Voltage: So called RCWV (Rated Continuous Working Voltage) is determined by

 $RCWV = \sqrt{RatedPower \times Resistance Value}$  or Max. RCWV listed above, whichever is lower.

# **DIMENSION(unit:mm)**

| Туре                  | Гуре WR02X(W)   |  |
|-----------------------|-----------------|--|
| L 0.60 ± 0.03         |                 |  |
| W                     | $0.30 \pm 0.03$ |  |
| T 0.23 ± 0.03         |                 |  |
| <b>Tb</b> 0.15 ± 0.05 |                 |  |
| <b>Tt</b> 0.10 ± 0.05 |                 |  |



### **MARKING**

WR02X(W) has no marking.



#### **FUNCTIONAL DESCRIPTION**

#### **Product characterization**

Standard values of nominal resistance are taken from the E24/E96 series for resistors with a tolerance of  $\pm 5\%$  &  $\pm 1\%$ . The values of the E24/E96 series are in accordance with "IEC publication 60063"

#### **Derating**

The power that the resistor can dissipate depends on the operating temperature; see Fig.2

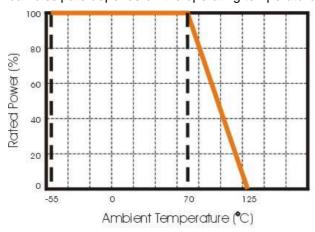


Figure 2. Maximum dissipation in percentage of rated power

As a function of the ambient temperature

#### **MOUNTING**

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.

#### **SOLDERING CONDITION**

The robust construction of chip resistors allows them to be completely immersed in a solder bath of 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 235°C during 2 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 3.

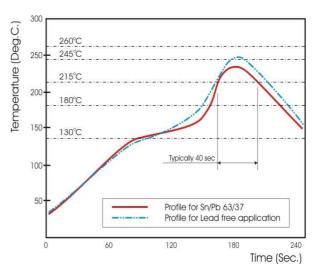


Fig 3. Infrared soldering profile for Chip Resistors WR02X(W)



#### **CATALOGUE NUMBERS**

The resistors have a catalogue number starting with:

| WR02        | х  | 472_   | J                    | Α  | R                            |
|-------------|--|--|----------------------|--|------------------------------|
| Size code   | Type code  | Resistance code  | Tolerance            | Packaging code   | RoHS code                    |
| WR02 : 0201 | $X: Normal$ $W: 1\%$ For <10 $\Omega$ and >1M $\Omega$ | $5\%$ , E24: 2 significant digits followed by no. of zeros and a blank. $100\Omega = 101\_$ $10KΩ = 103\_$ $1\%$ , E24+E96: 3 significant digits followed by no. of zeros $100\Omega = 1000$ $37.4KΩ = 3742$ | J:±5% F:±1% P:Jumper | A : 7" Reeled taping (15Kpcs/Reel)  T : 7" Reeled taping (10Kpcs/Reel) | R = Lead free<br>(< 100 ppm) |

LEAD content: below 100ppm with reference to IEC62321, determination of LEAD by ICP-AES

# **TEST AND REQUIREMENTS (JIS C 5201-1: 1998)**

Essentially all tests are carried out according to the schedule of IEC publication 115-8, category LCT/UCT/56(rated temperature range: Lower Category Temperature, Upper Category Temperature; damp heat, long term, 56 days). The testing also meets the requirements specified by EIA, EIAJ and JIS.

The tests are carried out in accordance with IEC publication 68, "Recommended basic climatic and mechanical robustness testing procedure for electronic components" and under standard atmospheric conditions according to IEC 60068-1, subclause 5.3. Unless otherwise specified, the following value supplied:

Temperature: 15°C to 35°C. Relative humidity: 45% to 75%.

Air pressure: 86kPa to 106 kPa (860 mbar to 1060 mbar). All soldering tests are performed with midly activated flux.

| TEST   | PROCEDURE / TEST METHOD   | REQUIREMENT                        |       |  |
|--|---|------------------------------------|-------|--|
| 1231   | PROCEDURE/TEST WIETHOD  | Resistor                           | 0Ω    |  |
| DC resistance                                | DC resistance values measured at the test voltages specified below:   |                                    |       |  |
| Clause 4.5                                   | <10Ω@0.1V, <100Ω@0.3V, <1KΩ@1.0V,   | Within the specified tolerance <50 |       |  |
|  | <10K $\Omega$ @3V, <100K $\Omega$ @10V, <1M $\Omega$ @25V, <10M $\Omega$ @30V   |                                    |       |  |
| Temperature Coefficient of Resistance(T.C.R) | Natural resistance change per change in degree centigrade.  | Refer to "QUICK REFERENCE DATA"    |       |  |
| Clause 4.8                                   | $\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/°C)}  t_1 : 20\text{°C} + 5\text{°C} - 1\text{°C}$  |                                    | N/a   |  |
|  | R <sub>1</sub> : Resistance at reference temperature  |                                    |       |  |
|  | R <sub>2</sub> : Resistance at test temperature   |                                    |       |  |
| Short time overload (S.T.O.L) Clause 4.13    | Permanent resistance change after a 2second application of a voltage 2.5 times RCWV or the maximum overload voltage specified in the above list, whichever is less. | $\Delta$ R/R max. ±(1%+0.05Ω)      | <50mΩ |  |

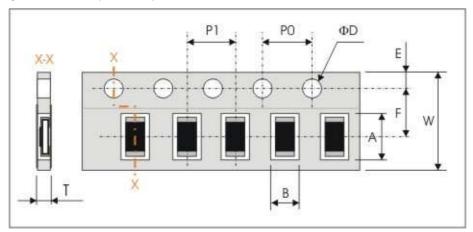


|                                     |  | Salara de la California | -               |  |
|-------------------------------------|--|--|-----------------|--|
| Resistance to soldering heat(R.S.H) | Un-mounted chips completely immersed for 10±1second in a SAC solder bath at 260°C±5°C  | $\Delta$ R/R max. $\pm$ (1%+0.05 $\Omega$ ) no visible damage  | 50mΩ            |  |
| Clause 4.18                         |  |  |                 |  |
| Solderability                       | Un-mounted chips completely immersed for 2±0.8second   | 95% coverage min., good tinning a  | and no          |  |
| Clause 4.17                         | in a SAC solder bath at 235°C±5°C  | visible damage   |                 |  |
| Temperature cycling Clause 4.19     | 30 minutes at -55°C±3°C, 2~3 minutes at 20℃+5℃-1℃, 30 minutes at +125°C±3°C, 2~3 minutes at 20℃+5℃-1℃, total 5 continuous cycles | $\Delta$ R/R max. ±(1%+0.05Ω) < 5  | 50mΩ            |  |
| Damp Heat                           | 1000 +48/-0 hours, loaded with RCWV or Vmax in   | $\Delta$ R/R max. ±(5%+0.10 $\Omega$ )   |                 |  |
| (Load life in humidity)             | humidity chamber controller at 40°C±2°C and 90~95%   | < 5  | $50$ m $\Omega$ |  |
| Clause 4.24                         | relative humidity,   |  |                 |  |
| Load Life (Endurance)  Clause 4.25  | 1000+48/-0 hours; loaded with RCWV or V <sub>max</sub> in chamber controller 70±2°C, 1.5 hours on and 0.5 hours off              | $\Delta$ R/R max. $\pm$ (5%+0.10 $\Omega$ )  | $50$ m $\Omega$ |  |
| High temperature Clause 4.25        | 125'C x 1000hrs, no load   | $\Delta$ R/R max. ±(5%+0.10 $\Omega$ ) < 5   | 50mΩ            |  |
| Bending strength                    | Resistors mounted on a 90mm glass epoxy resin  |  |                 |  |
| Clause 4.33                         | PCB(FR4), bending once 3mm for 10sec.  | $\Delta$ R/R max. $\pm$ (1%+0.05 $\Omega$ )  | < 50mΩ          |  |
| Adhesion                            | Pressurizing force: 3N, Test time: 10±1sec.  | No remarkable damage or removal of the   |                 |  |
| Clause 4.32                         |  | terminations   |                 |  |



## **PACKAGING**

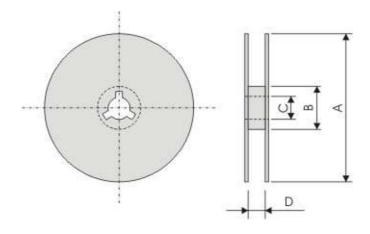
# Paper Tape specifications (unit :mm)



| Series No. | А         | В         | W         | F         | E         |
|------------|-----------|-----------|-----------|-----------|-----------|
| WR02X      | 0.67±0.05 | 0.37±0.05 | 8.00±0.20 | 3.50±0.05 | 1.75±0.10 |

| Series No. | P1        | P0        | ΦD                           | Т         |
|------------|-----------|-----------|------------------------------|-----------|
| WR02X      | 2.00±0.05 | 4.00±0.05 | $\Phi$ 1.50 $^{+0.1}_{-0.0}$ | 0.45±0.05 |

#### **Reel dimensions**



| Symbol      | Α             | В          | С        | D        |
|-------------|---------------|------------|----------|----------|
| (unit : mm) | Ф180.0+0/-1.5 | Φ60.0±1.0  | 13.0±0.2 | 9.0+1/-0 |
|             |               | Φ60.0+1/-0 |          |          |

# **Taping quantity and Tape material**

- Chip resistors 15,000 pcs/reel, Paper tape.